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<i>David Weyers (Technical University of Dresden, Germany), Akash Mistry (Technical University of Dresden, Germany), Krzysztof Niewegłowski (Technical University of Dresden, Germany), and Karlheinz Bock (Technical University of Dresden, Germany)</i>	

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<i>Haoxiang Ren (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA), Saptadeep Pal (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA), Guangqi Ouyang (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA), Randall Irwin (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA), Yu-Tao Yang (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA), and Subramanian S. Iyer (Center for Heterogeneous Integration and Performance Scaling (CHIPS), UCLA, USA)</i>	
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<i>Mohamed Abdelatty (State University of New York at Binghamton, USA), Ashraf Umar (State University of New York at Binghamton, USA), Gurvinder S. Khinda (State University of New York at Binghamton, USA), Mohammed Alhendi (State University of New York at Binghamton, USA), and Mark D. Poliks (State University of New York at Binghamton, USA)</i>	
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<i>Priyank Kashyap (North Carolina State University, USA), Yongjin Choi (Hewlett Packard Enterprise), Sumon Dey (Hewlett Packard Enterprise), Dror Baron (North Carolina State University, USA), Chau-Wai Wong (North Carolina State University, USA), Tianfu Wu (North Carolina State University, USA), Chris Cheng (Hewlett Packard Enterprise), and Paul D. Franzon (North Carolina State University, USA)</i>	

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<i>Daisuke Hironiwa (Semiconductor & Electronics Equipment Division, ULVAC, Inc., Japan), Haw Wen Chen (Management Planning Group, ULVAC TAIWAN, Inc., Taiwan R.O.C), Yasuhiro Morikawa (Institute of Advanced Technology, ULVAC, Inc., Japan), Takashi Kurimoto (Semiconductor & Electronics Equipment Division, ULVAC, Inc., Japan), and Ryuichiro Kamimura (Semiconductor & Electronics Equipment Division, ULVAC, Inc., Japan)</i>	
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<i>Teck-Chong Lee (Advanced Semiconductor Engineering Inc., Taiwan), Shu-Han Yang (Advanced Semiconductor Engineering Inc., Taiwan), Hsin-Yi Wu (Advanced Semiconductor Engineering Inc., Taiwan), and You-Jun Lin (Advanced Semiconductor Engineering Inc., Taiwan)</i>	
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<i>Guilian Gao (Xperi, USA), Laura Mirkarimi (Xperi, USA), Gill Fountain (Xperi, USA), Dominik Suwito (Xperi, USA), Jeremy Theil (Xperi, USA), Thomas Workman (Xperi, USA), Cyprian Uzoh (Xperi, USA), Bongsub Lee (Xperi, USA), Km Bang (Xperi, USA), and Gabe Guevara (Xperi, USA)</i>	
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<i>Ser Choong Chong (Institute of Microelectronics, Singapore), Cereno Daniel Ismael (Institute of Microelectronics, Singapore), Pei Siang Lim (Institute of Microelectronics, Singapore), Cheng Yi Shim (Institute of Microelectronics, Singapore), Wai Song Lai (Institute of Microelectronics, Singapore), and Woon Leng Loh (Institute of Microelectronics, Singapore)</i>	
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<i>Rick Ye (Siliconware Precision Industries Co. Ltd, Taiwan (R.O.C.)), Eric Chen (Siliconware Precision Industries Co. Ltd, Taiwan (R.O.C.)), Wen-Yu Teng (Siliconware Precision Industries Co. Ltd, Taiwan (R.O.C.)), Andrew Kang (Siliconware Precision Industries Co. Ltd, Taiwan (R.O.C.)), and Yu-Po Wang (Siliconware Precision Industries Co. Ltd, Taiwan (R.O.C.))</i>	
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<i>SeokHo Na (Amkor Technology Korea, Korea), MinHo Gim (Amkor Technology Korea, Korea), ChoongHoe Kim (Amkor Technology Korea, Korea), DongHyeon Park (Amkor Technology Korea, Korea), DongSu Ryu (Amkor Technology Korea, Korea), DongJoo Park (Amkor Technology Korea, Korea), and JinYoung Khim (Amkor Technology Korea, Korea)</i>	
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<i>Daiki Yukimori (Taiyo Holdings Co., Ltd., Japan), Go Inoue (Taiyo Holdings Co., Ltd., Japan), Nobuhiro Ishikawa (Taiyo Holdings Co., Ltd., Japan), Atsushi Sekiguchi (Osaka Metropolitan University, Japan; Litho Tech Japan corporation, Japan), and Toshiyuki Ogata (Taiyo Holdings Co., Ltd., Japan)</i>	

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<i>Wooyoung Kim (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea), Yongin Lee (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea), Wonyoung Choi (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea), Kyeongbin Lim (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea), BumKi Moon (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea), and Daniel Minwoo Rhee (Mechatronics Research, Samsung electronics Co. Ltd, Republic of Korea)</i>	
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<i>Jiaxiong Li (Georgia Institute of Technology, USA), John Wilson (Georgia Institute of Technology, USA), Dylan Cheung (Georgia Institute of Technology, USA), Zhijian Sun (Georgia Institute of Technology, USA), Kyoung-Sik Moon (Georgia Institute of Technology, USA), Madhavan Swaminathan (Georgia Institute of Technology, USA), and Ching-Ping Wong (Georgia Institute of Technology, USA)</i>	
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